Abstracts

Development of a package utilizing an electromagnetic coupling structure

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We have developed a new package for millimeter wave systems. This package employs a feed-through, which utilizes an electromagnetic coupling structure. The chosen electromagnetic coupling structure for the package consists of microstrip line/slot/microstrip line and has a low insertion loss. The insertion loss at the electromagnetic coupling part is estimated to be about 0.3 dB at 60 GHz when the structure is made from conventional alumina material. The package is produced by means of ordinary lamination technology which involves tape casting, printing, laminating and co-firing. High performance is compatible with low cost in this package, and it is suitable for new and big markets utilizing millimeter wave frequencies.

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